



■ CIRCUIT TRACE KEEP OUT AREA
 ■ SMT SOLDER AREA

THERE SHOULD NOT BE ANY CIRCUITRIES IN THE LAYOUT SPACE OF THE PRODUCTS.

RECOMMENDED PCB LAYOUT
 GENERAL TOLERANCE ±0.05

| SIM pin Assignment | |
|--------------------|------|
| PIN# | Name |
| C1 | VCC |
| C2 | RST |
| C3 | CLK |
| C5 | GND |
| C6 | VPP |
| C7 | I/O |

NOTES:

MATERIAL:
 Insulator: High Temperature Thermoplastic,
 Contact: Copper Alloy
 Shell: STAINLESS
 PLATING:
 Contact: Plated 30u" Ni Overall ,Solder Area: Tin,Contact G/F
 Shell: Plated 30u" Ni Overall
 Plated G/F Selective Contact Area
 Electrical:
 Current Rating :0.5mA max.
 Voltage Rating :50V DC MAX
 Ambient Temperature Range :-20°C~+85°C
 Storage Temperature Range :-40°C~+70°C
 Ambient Humidity Range :95% R.H. Max.
 Contact Resistance:100m max.
 Insulation Resistance:1000M min./250V DC
 Dielectric Withstanding Voltage:500V AC
 Mating Cycles:5,000 Insertions
 Temperature: 260°C ±5°

| ITEM | PAPT NAMF | QTY | MATERIAL | FINISHING |
|------|-----------|-----|-------------------------|-----------|
| ③ | Shell | 1 | SUS | |
| ② | Terminal | 6 | COPPER ALLOY | |
| ① | Housing | 1 | HI-TEMP.PLASIC UL 94V-0 | BLACK |

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| | |
|---|----|
| 生 | 日期 |
| 效 | 日期 |

| MARK | DESCRIPTION | DATE | REVISED | APPROVED | REVISIONS |
|------|-------------|------|---------|----------|-----------|
| 文件 | 工程 | | | | |

| | | | | |
|--------------------------------------|--|------|-------------|------------------------------|
| DSND | | DATE | SCALE: N/A | MODEL TYPE: SIM CARD CONN |
| DWN | | DATE | VIEW: | PART NO.: |
| CHKD | | DATE | UNIT: mm/in | DWG NO.: |
| APPD | | DATE | SIZE: A4 | XKSIM-002-P6 |
| XKB INDUSTRIAL PRECISION CO.,LIMITED | | | | WEIGHT 1.0g |
| | | | | SHEET 1/1 |
| | | | | REVISION A0 |

单击下面可查看定价，库存，交付和生命周期等信息

[>>XKB Connectivity\(中国星坤\)](#)